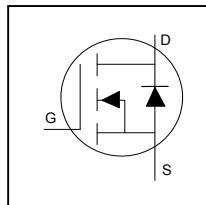


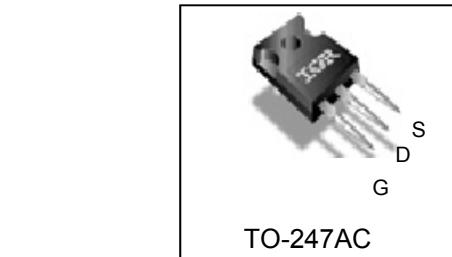
Features

- Advanced Process Technology
- Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to T_{jmax}
- Lead-Free, RoHS Compliant
- Automotive Qualified *



HEXFET® Power MOSFET

V_{DSS}	300V
$R_{DS(on)}$ typ. max	56mΩ
	69mΩ
I_D	38A



G	D	S
Gate	Drain	Source

Description

Specifically designed for Automotive applications, this HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFP4409	TO-247AC	Tube	25	AUIRFP4409

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I_D @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	38	A
I_D @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	27	
I_{DM}	Pulsed Drain Current ①	152	
P_D @ $T_C = 25^\circ\text{C}$	Maximum Power Dissipation	341	W
	Linear Derating Factor	2.3	W/ $^\circ\text{C}$
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS} (Thermally limited)	Single Pulse Avalanche Energy ②	541	mJ
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	$^\circ\text{C}$
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N·m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ③	—	0.44	$^\circ\text{C/W}$
$R_{\theta CS}$	Case-to-Sink, Flat Greased Surface	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient ⑦	—	40	

HEXFET® is a registered trademark of International Rectifier.

*Qualification standards can be found at <http://www.irf.com/>

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	300	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	0.24	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 3.5\text{mA}$
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	56	69	$\text{m}\Omega$	$V_{GS} = 10V, I_D = 24\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	3.0	—	5.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 300\text{ V}, V_{GS} = 0\text{V}$
		—	—	250		$V_{DS} = 300\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20\text{V}$
R_G	Gate Resistance	—	1.3	—	Ω	

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

g_{fs}	Forward Transconductance	45	—	—	S	$V_{DS} = 50\text{V}, I_D = 24\text{A}$
Q_g	Total Gate Charge	—	83	125	nC	$I_D = 24\text{A}$
Q_{gs}	Gate-to-Source Charge	—	28	42		$V_{DS} = 150\text{V}$
Q_{gd}	Gate-to-Drain Charge	—	26	39		$V_{GS} = 10\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	—	18	—	ns	$V_{DD} = 195\text{V}$
t_r	Rise Time	—	23	—		$I_D = 24\text{A}$
$t_{d(\text{off})}$	Turn-Off Delay Time	—	34	—		$R_G = 2.2\Omega$
t_f	Fall Time	—	20	—		$V_{GS} = 10\text{V}$
C_{iss}	Input Capacitance	—	5168	—	pF	$V_{GS} = 0\text{V}$
C_{oss}	Output Capacitance	—	300	—		$V_{DS} = 50\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	77	—		$f = 1.0\text{MHz}$
$C_{oss \text{ eff. (ER)}}$	Effective Output Capacitance (Energy Related)	—	196	—		$V_{GS} = 0\text{V}, V_{DS} = 0\text{V} \text{ to } 240\text{V}$ ⑥ See Fig.11
$C_{oss \text{ eff. (TR)}}$	Output Capacitance (Time Related)	—	265	—		$V_{GS} = 0\text{V}, V_{DS} = 0\text{V} \text{ to } 240\text{V}$ ⑤

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_s	Continuous Source Current (Body Diode) ①	—	—	40	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{sM}	Pulsed Source Current (Body Diode) ①	—	—	160		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_s = 24\text{A}, V_{GS} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	302	—	ns	$T_J = 25^\circ\text{C} \quad V_{DD} = 255\text{V}$
		—	379	—		$T_J = 125^\circ\text{C} \quad I_F = 24\text{A},$
Q_{rr}	Reverse Recovery Charge	—	1739	—	nC	$T_J = 25^\circ\text{C} \quad \text{di/dt} = 100\text{A}/\mu\text{s}$ ④
		—	2497	—		$T_J = 125^\circ\text{C}$
I_{RRM}	Reverse Recovery Current	—	13	—	A	$T_J = 25^\circ\text{C}$

Notes:

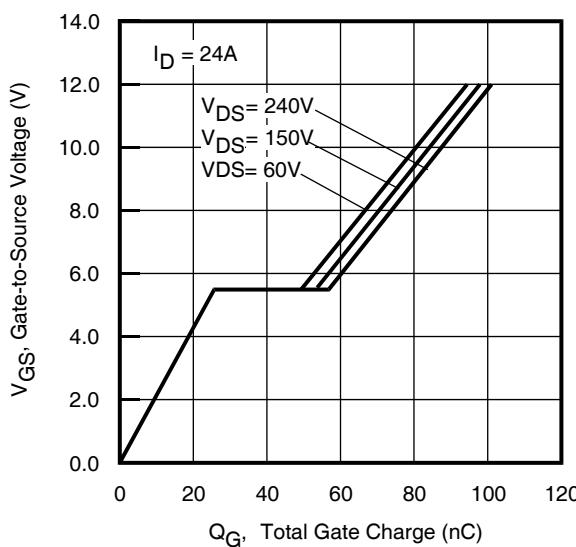
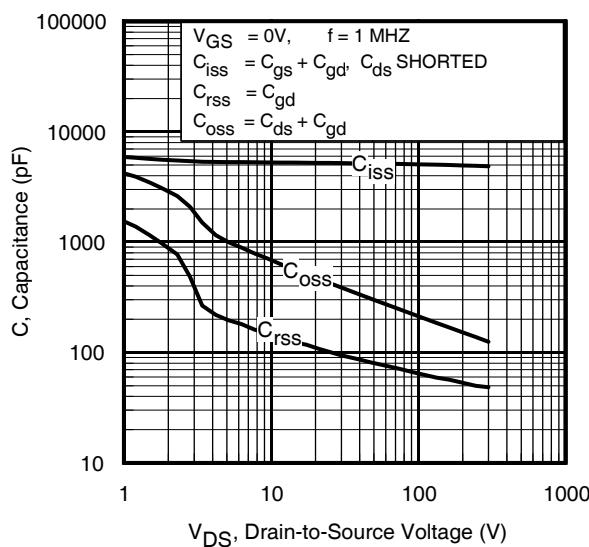
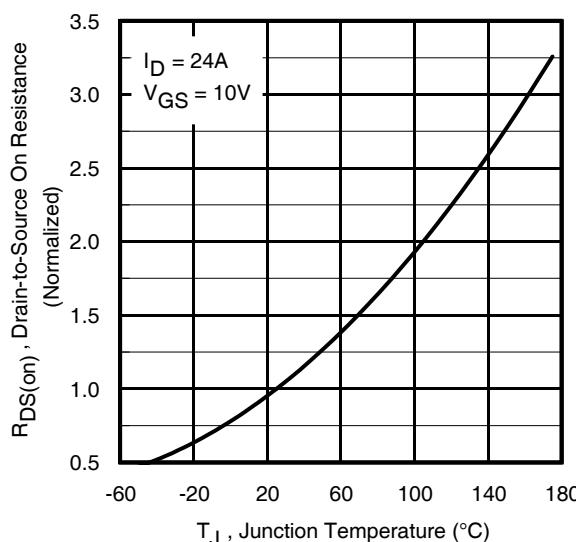
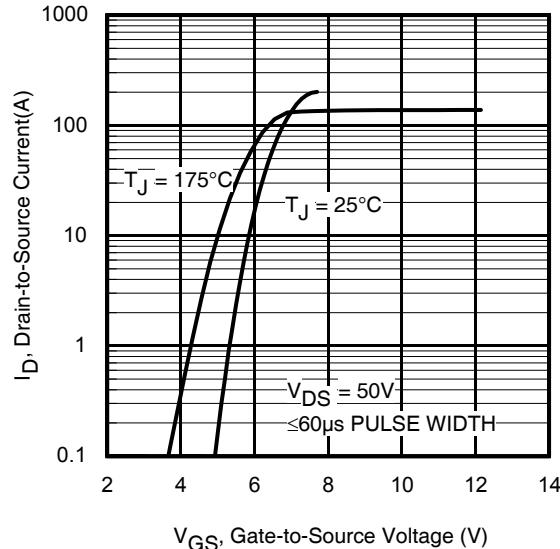
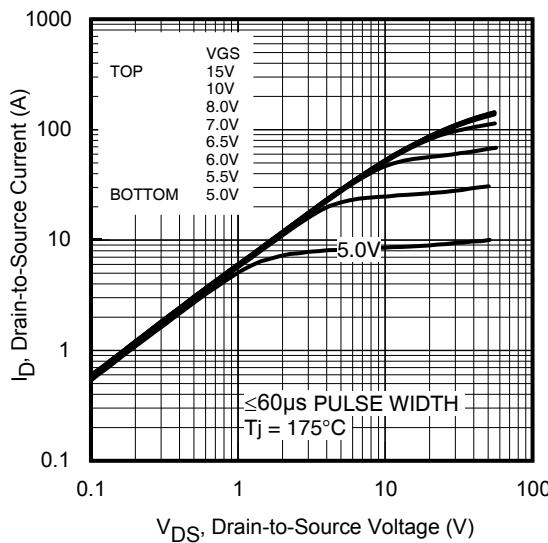
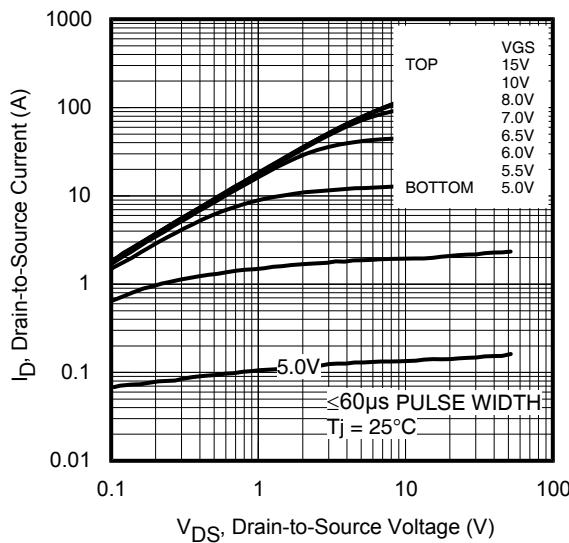
- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Recommended max EAS limit, starting $T_J = 25^\circ\text{C}$, $L = 2.05\text{mH}$, $R_G = 50\Omega$, $I_{AS} = 24\text{A}$, $V_{GS} = 10\text{V}$.
- ③ $I_{SD} \leq 24\text{A}$, $\text{di/dt} \leq 1771\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$.
- ④ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑤ $C_{oss \text{ eff. (TR)}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑥ $C_{oss \text{ eff. (ER)}}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑦ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994 <http://www.irf.com/technical-info/app-notes/an-994.pdf>
- ⑧ R_θ is measured at T_J approximately 90°C

Qualification Information[†]

	Automotive (per AEC-Q101)	
Qualification Level	Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
ESD	TO-247AC	N/A
	Machine Model	Class M4 (+/- 500V) ^{††} AEC-Q101-002
	Human Body Model	Class H2 (+/- 4000V) ^{††} AEC-Q101-001
	Charged Device Model	Class C5 (+/- 2000) ^{††} AEC-Q101-005
RoHS Compliant	Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Highest passing voltage.



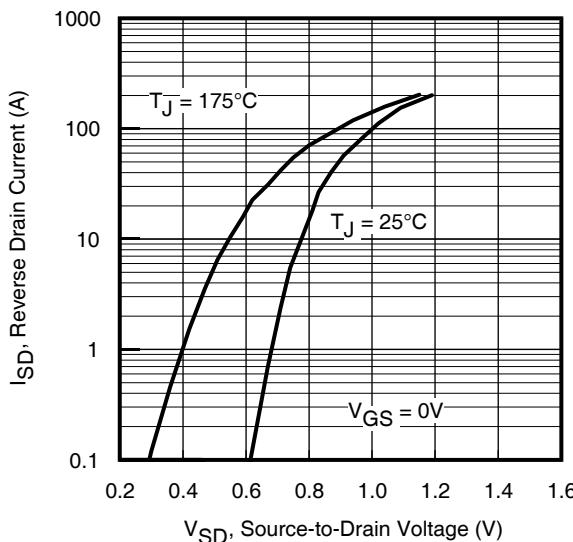


Fig 7. Typical Source-Drain Diode Forward Voltage

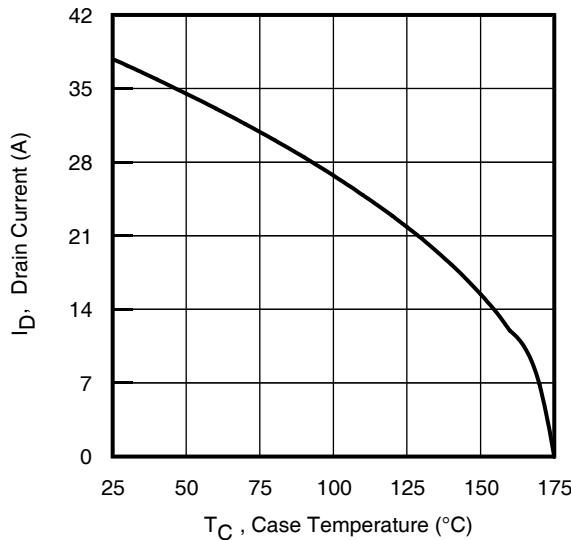


Fig 9. Maximum Drain Current vs. Case Temperature

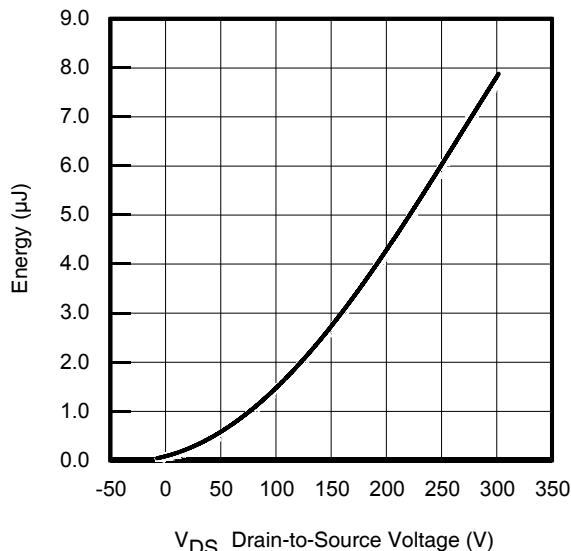


Fig 11. Typical C_{oss} Stored Energy

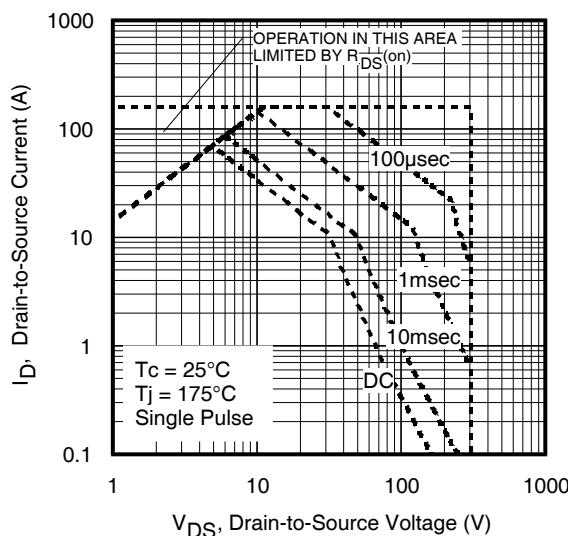


Fig 8. Maximum Safe Operating Area

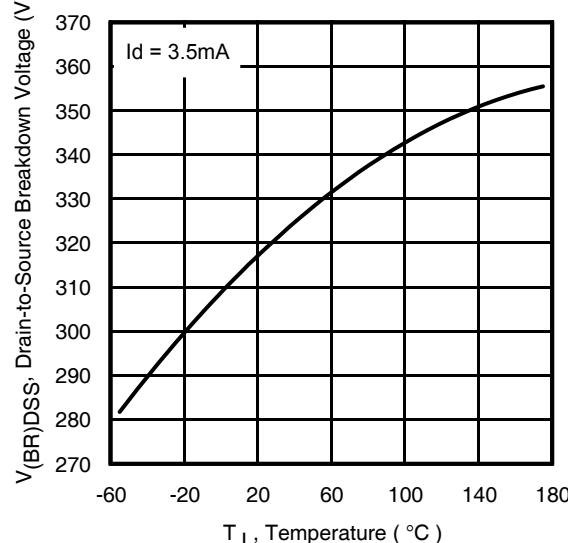


Fig 10. Drain-to-Source Breakdown Voltage

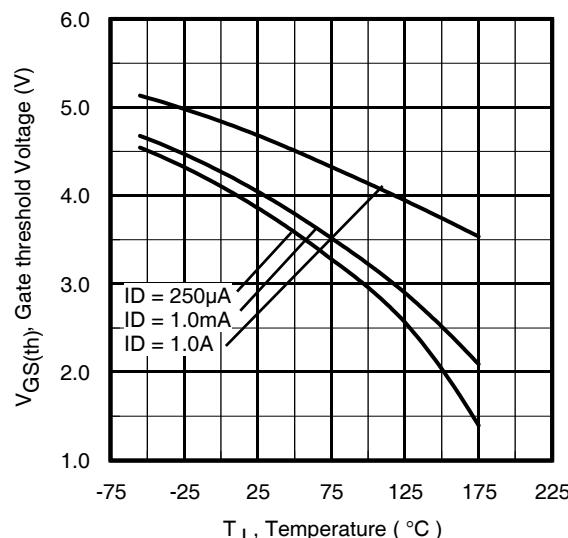


Fig 12. Threshold Voltage vs. Temperature

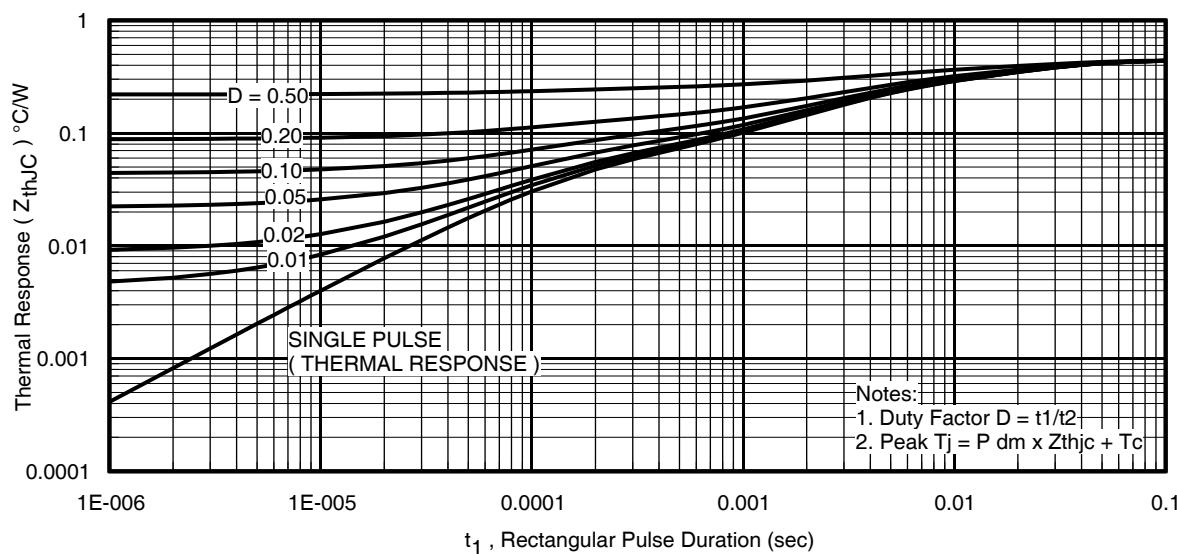


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

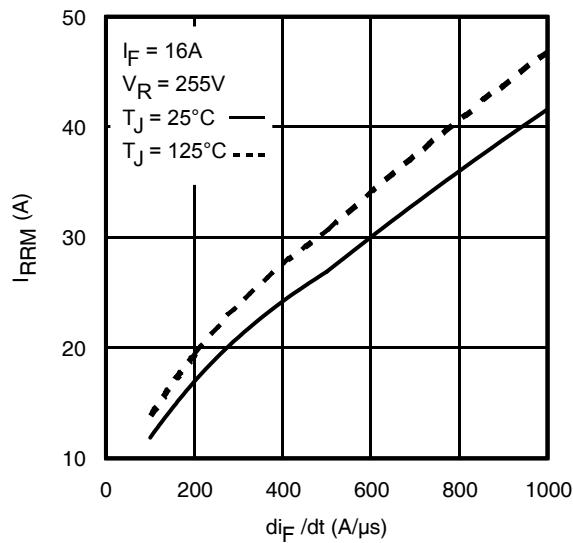


Fig 14. Typical Recovery Current vs. di/dt

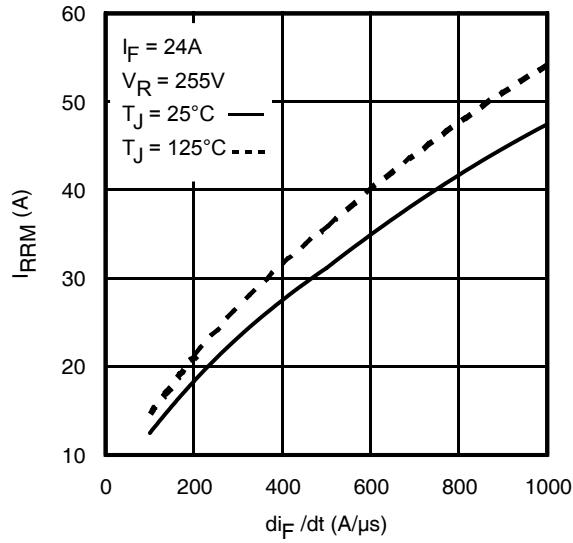


Fig 15. Typical Recovery Current vs. di/dt

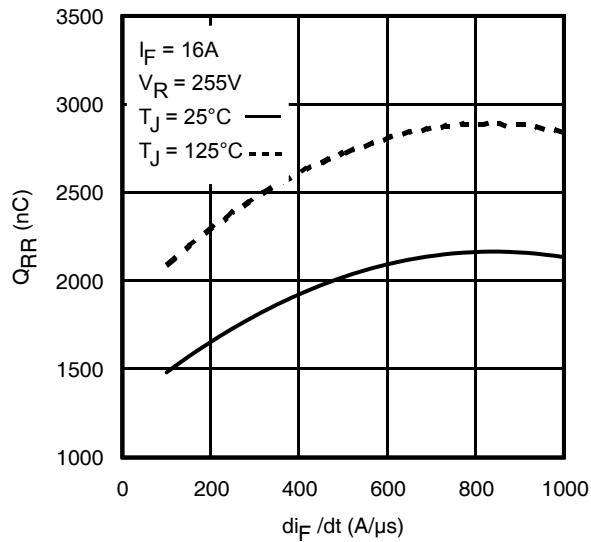


Fig 16. Typical Stored Charge vs. di/dt

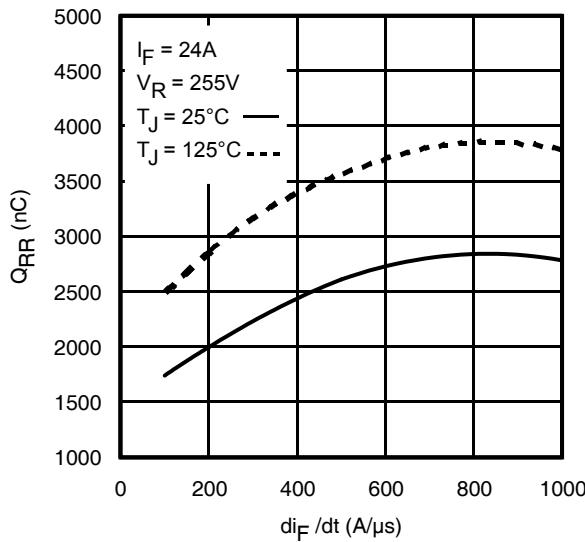


Fig 17. Typical Stored Charge vs. di/dt

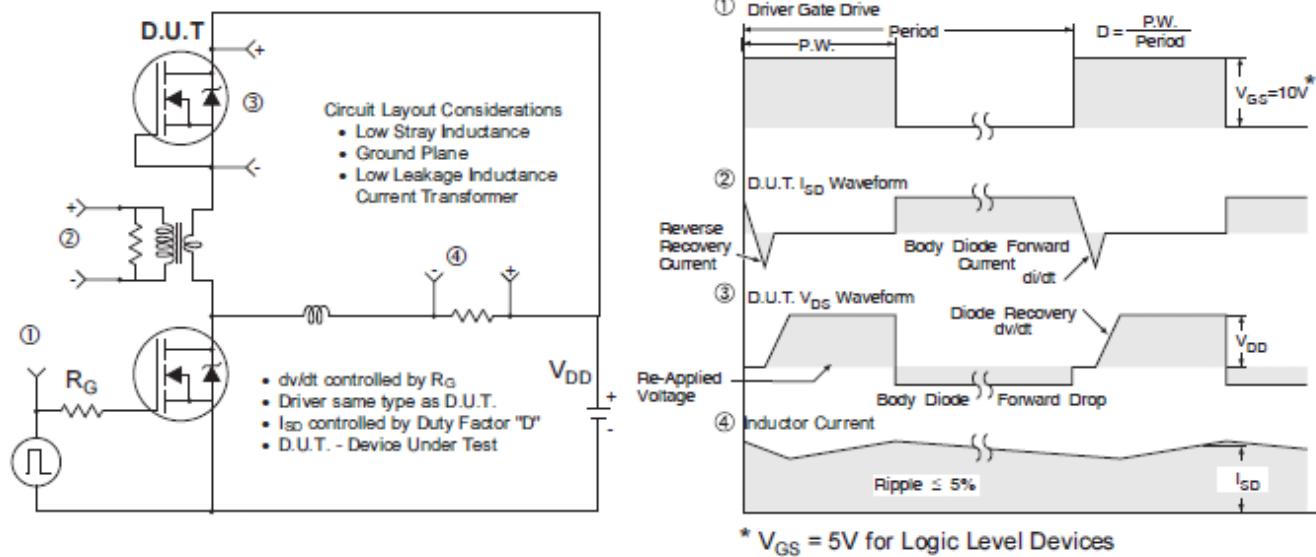


Fig 18. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

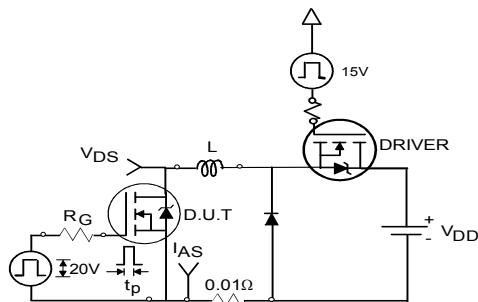


Fig 19a. Unclamped Inductive Test Circuit

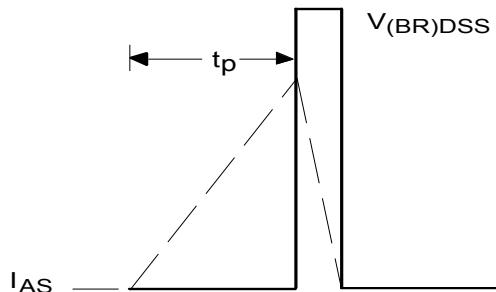


Fig 19b. Unclamped Inductive Waveforms

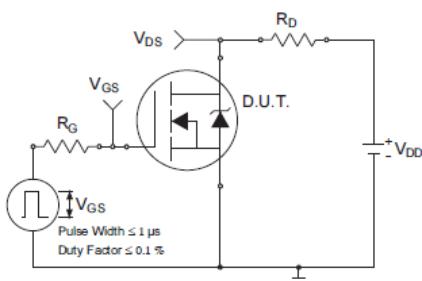


Fig 20a. Switching Time Test Circuit

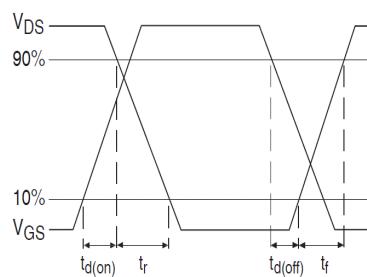


Fig 20b. Switching Time Waveforms

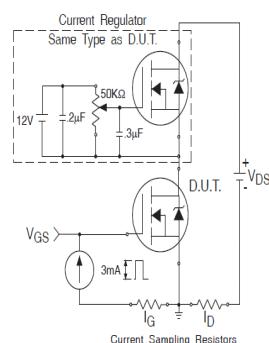


Fig 21a. Gate Charge Test Circuit

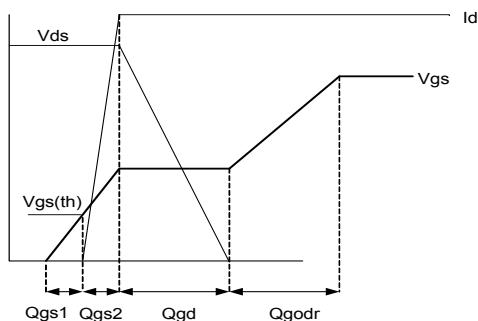
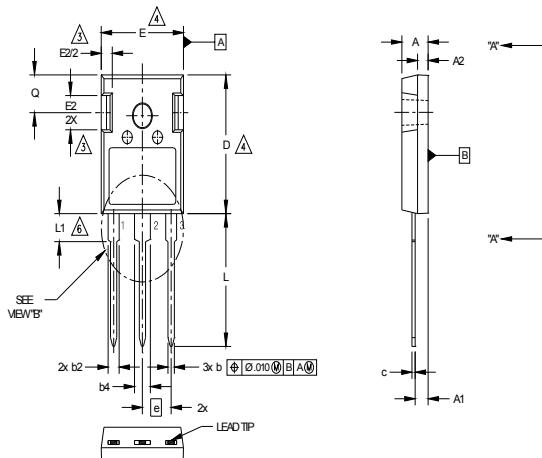


Fig 21b. Gate Charge Waveform

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



SYMBOL	DIMENSIONS				NOTES	
	INCHES		MILLIMETERS			
	MIN.	MAX.	MIN.	MAX.		
A	.190	.204	4.83	5.20		
A1	.090	.100	2.29	2.54		
A2	.075	.085	1.91	2.16		
b	.042	.052	1.07	1.33		
b2	.075	.094	1.91	2.41		
b4	.113	.133	2.87	3.38		
c	.022	.026	0.55	0.68		
D	.819	.830	20.80	21.10		
D1	.640	.694	16.25	17.65		
E	.620	.635	15.75	16.13		
E1	.512	.570	13.00	14.50		
E2	.145	.196	3.68	5.00		
e	.215	Typical	5.45	Typical		
L	.780	.800	19.80	20.32		
L1	.161	.173	4.10	4.40		
Ø P	.138	.143	3.51	3.65		
Q	.216	.236	5.49	6.00		
S	.238	.248	6.04	6.30		

LEAD ASSIGNMENTS

HEXFET

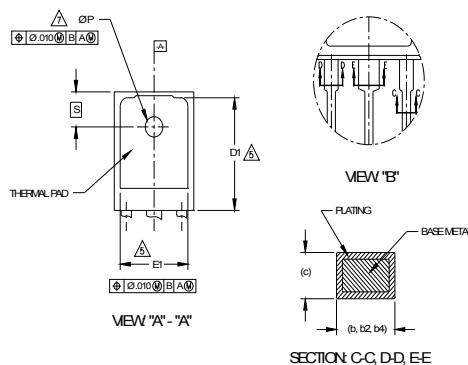
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- Emitter
- 4.- COLLECTOR

DIODES

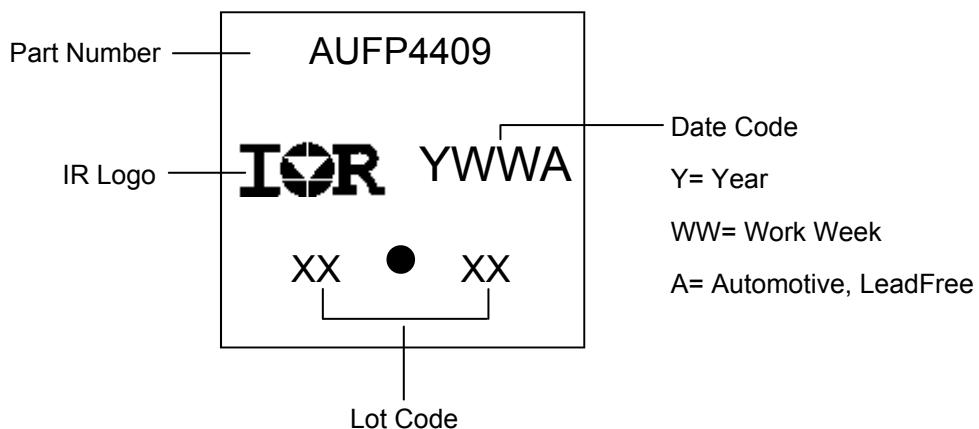
- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE



NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
2. DIMENSIONS ARE SHOWN IN INCHES AND MILLIMETERS.
3. CONTOUR OF SLOT OPTIONAL.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
6. LEAD FINISH UNCONTROLLED IN L1.
7. Ø P TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.

TO-247AC Part Marking Information



TO-247AC package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

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<http://www.irf.com/technical-info/>

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